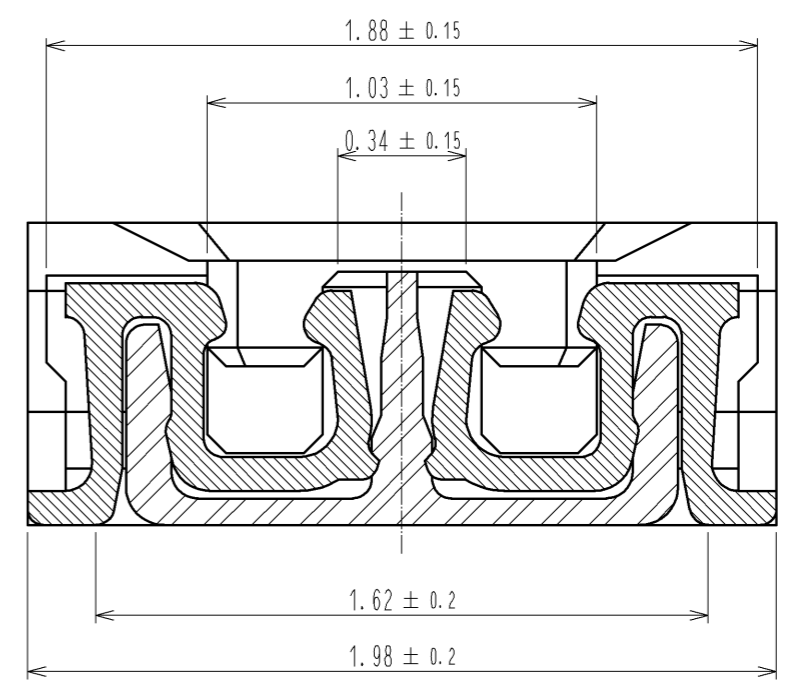
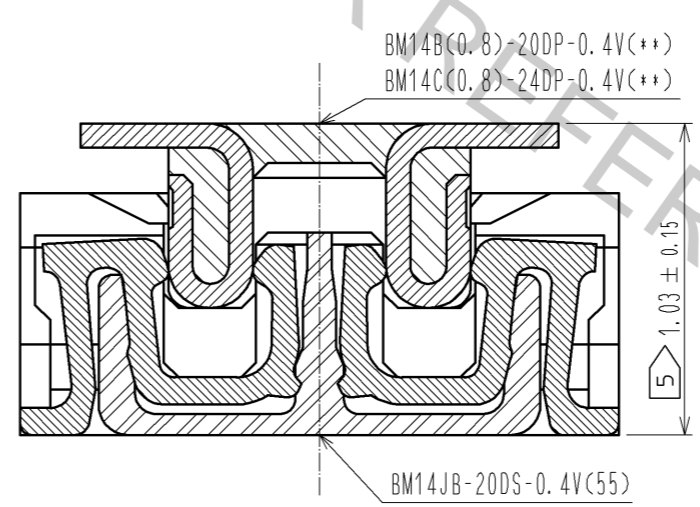


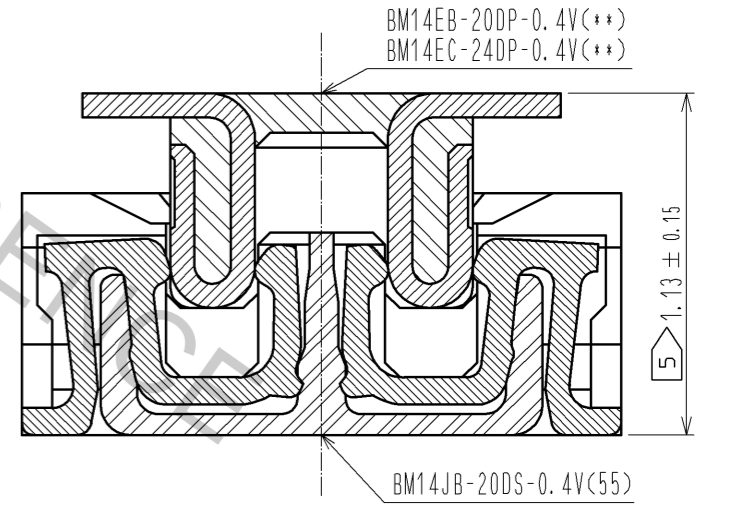
A-A (FREE)



ENGAGEMENT FIGURE (FREE)



ENGAGEMENT FIGURE (FREE)



- NOTE) 1. ALL LEAD CO-PLANARITY SHALL BE 0.08mm MAX
 2. CONTACT PLATING SPECIFICATIONS.
 CONTACT AREA : GOLD 0.05 μm MIN
 SMT LEAD : GOLD 0.05 μm MIN
 UNDERPLATING : NICKEL 1 μm MIN
 (SURFACE : SEALING)
 3. EACH CONTACTS AT 4 CORNERS ARE PROVIDED FOR METAL FITTINGS AND GROUNDING PURPOSE.
 4. HRS MARK AND CAV NO. ARE INDICATED IN APPROX POSITION SHOWN.
 5. GATE POSITION IS INDICATED IN APPROX POSITION SHOWN.
 6. THE DIMENSIONS INDICATED IN THE FIGURE IS REFERENCE.
 AN ELECTRIC PERFORMANCE IS GUARANTEED BY BEING MAINTAINED AS SHOWN IN THE FIGURE.

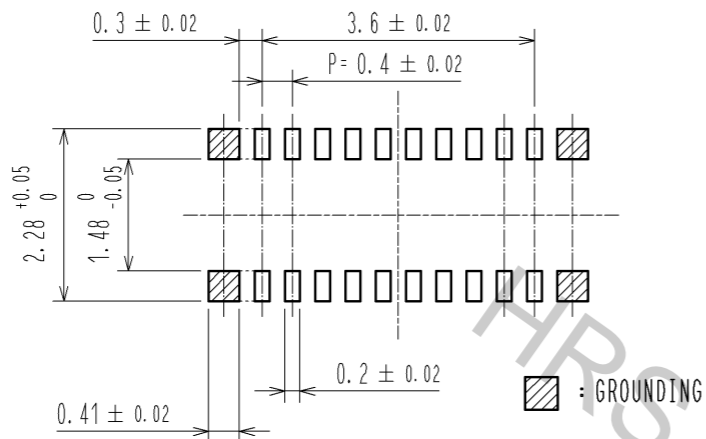
SPECIMEN	
BM14B(0.8)-20DP-0.4V(**)	BM14C(0.8)-24DP-0.4V(**)
BM14EB-20DP-0.4V(**)	BM14EC-24DP-0.4V(**)

NO.	MATERIAL	FINISH	REMARKS	NO.	MATERIAL	FINISH	REMARKS
3	PS		CLEAR(ENBOSSED CARRIER TAPE)	6	PS		CLEAR(REINFORCEMENT COLLAR)
2	PHOSPHOR BRONZE	2		5	PS		BLACK(PLASTIC REEL)
1	LCP		UL94 V-0, BLACK	4	POLYESTER		CLEAR(COVER TAPE)

UNITS	SCALE	COUNT	DESCRIPTION OF REVISIONS	DESIGNED	CHECKED	DATE
mm	10:1	7	DIS-H-005964	YN. SAKAMOTO	AR. TAKAHASHI	11.07.11

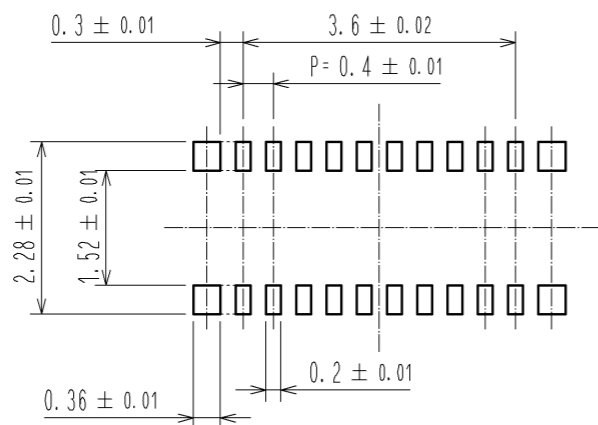
APPROVED	CHECKED	DESIGNED	DRAWN	DRAWING NO.	PART NO.	CODE NO.
KH. IKEDA	TS. MIYAZAKI	SH. HOSODA	SH. HOSODA	EDC3-331560-01	BM14JB-20DS-0.4V(55)	CL684-8226-0-55
10.05.13	10.05.13	10.05.11	10.05.11			

◆ RECOMMENDED PCB LAYOUT



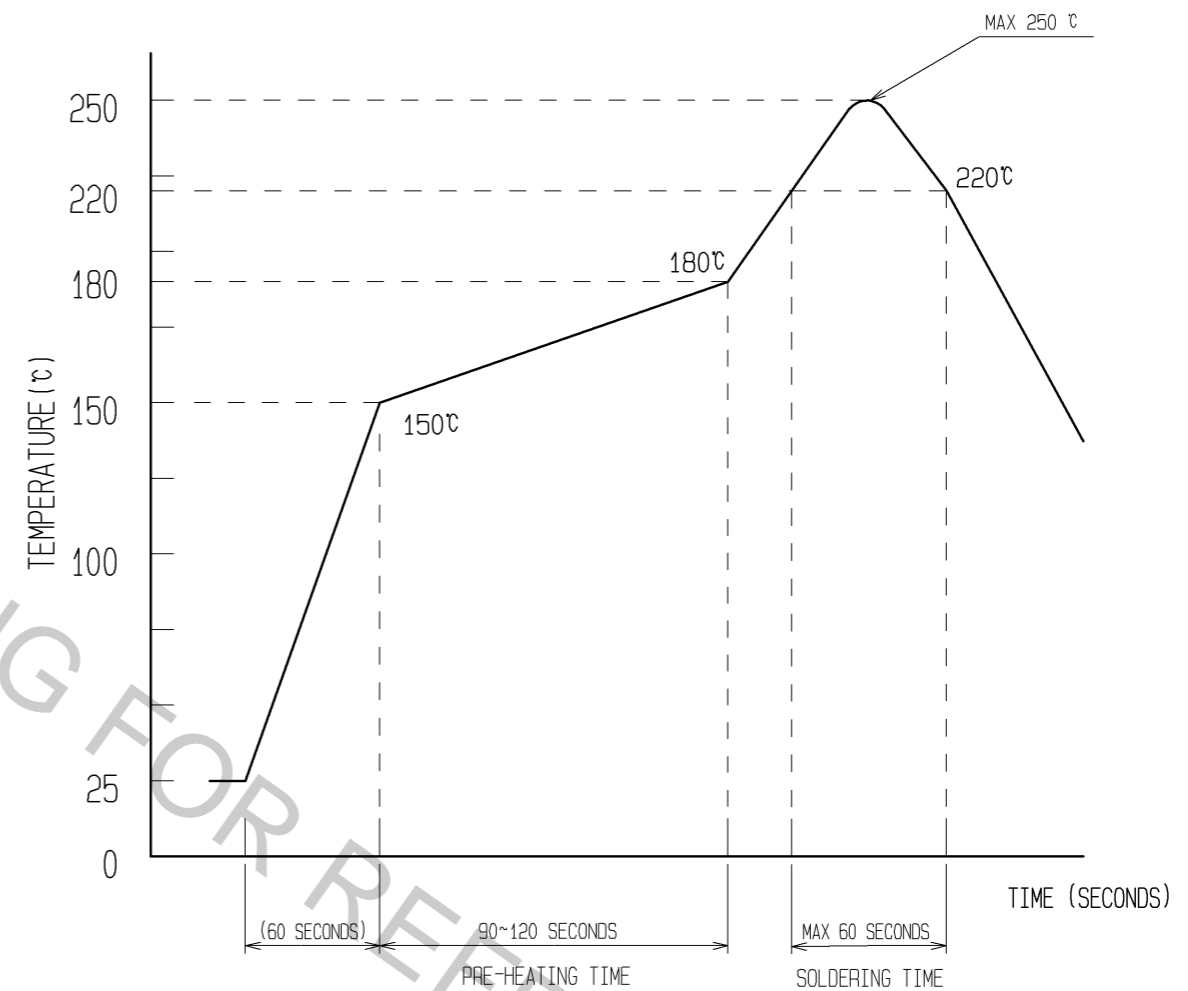
◆ RECOMMENDED METAL MASK DIMENSIONS

METAL MASK THICKNESS : 100 μm



△
<削除>

7) RECOMMENDED REFLOW TEMPERATURE PROFILE USING LEAD-FREE SOLDER PASTE.



- REFLOW METHOD: IR REFLOW.
 NUMBER OF REFLOW CYCLES: 2 CYCLES MAX.
- 1) REFLOW TIME
 DURATION ABOVE 220°C, 60 SEC. MAX.
 (PEAK TEMPERATURE: 250°C MAX)
 - 2) PRE-HEAT TIME
 PRE-HEAT TEMPERATURE(MIN): 150°C
 PRE-HEAT TEMPERATURE(MAX): 180°C
 PRE-HEAT TIME: 90-120 sec.

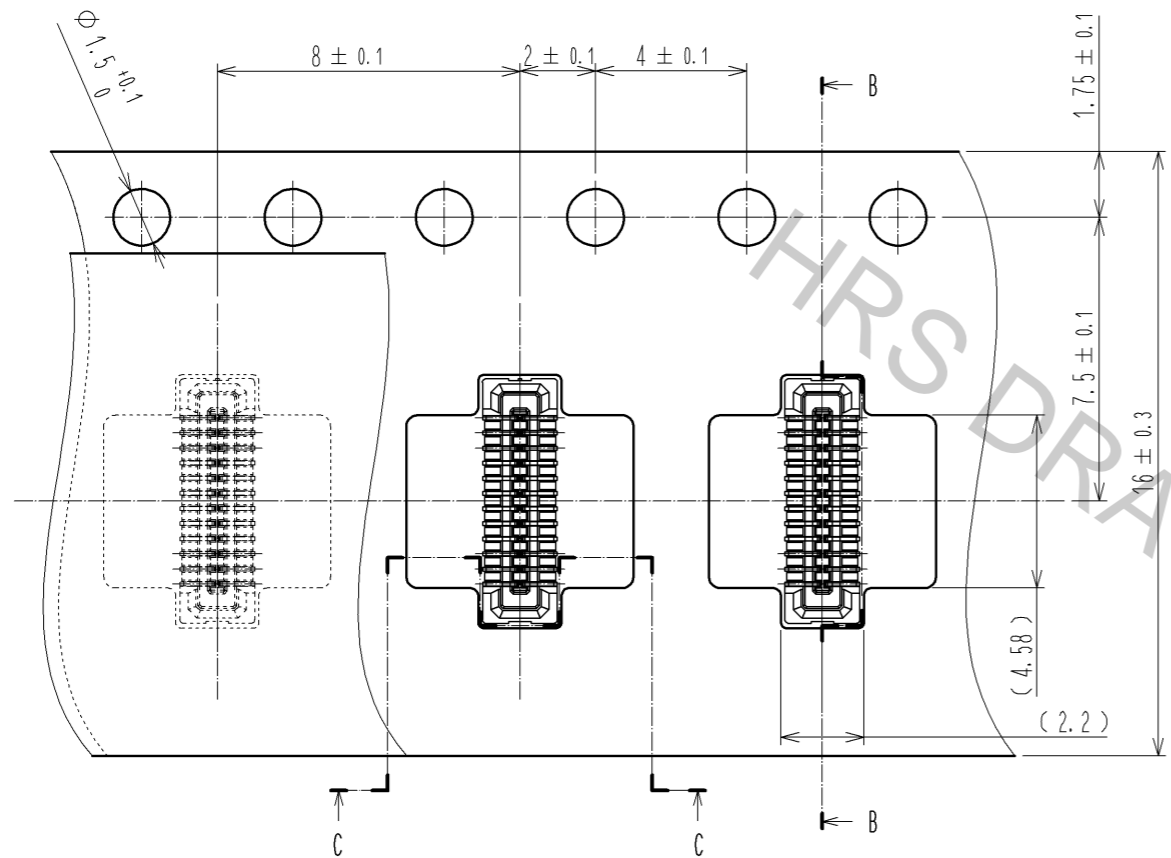
7) THIS TEMPERATURE PROFILE IS PER THE CONDITIONS SHOWN ABOVE. ADDITIONAL FACTORS, SUCH AS SOLDER PASTE TYPE, PCB SIZE AND OTHER MOUNTED COMPONENTS COULD AFFECT THE PROFILE, THEREFORE, A THOROUGH EVALUATION OF MOUNTING CONDITION IS REQUIRED PRIOR TO PRODUCTION. TEMPERATURE IS MEASURED AT CONTACT LEAD.

HRS	DRAWING NO.	EDC3-331560-01
	PART NO.	BM14JB-20DS-0.4V(55)
	CODE NO.	CL684-8226-0-55

△ 2/3

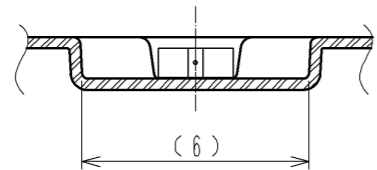
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EMBOSSED CARRIER TAPE PACKAGING (5:1)

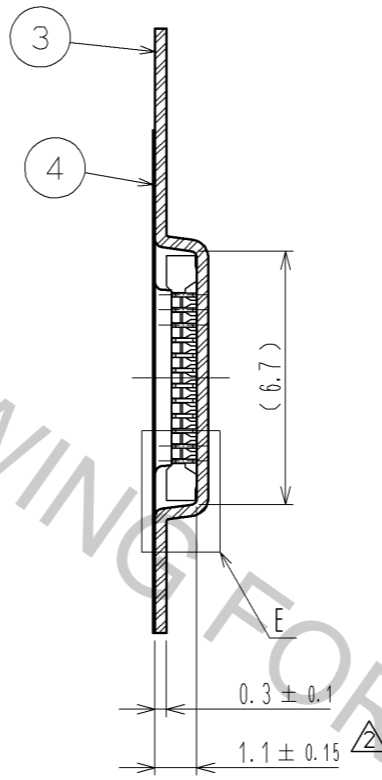


DIRECTION OF UNREELING
→

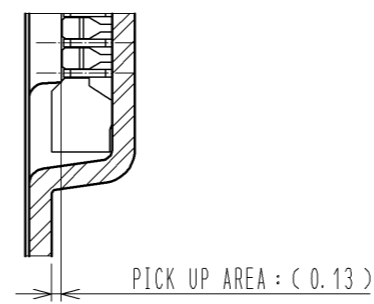
C-C (5:1)



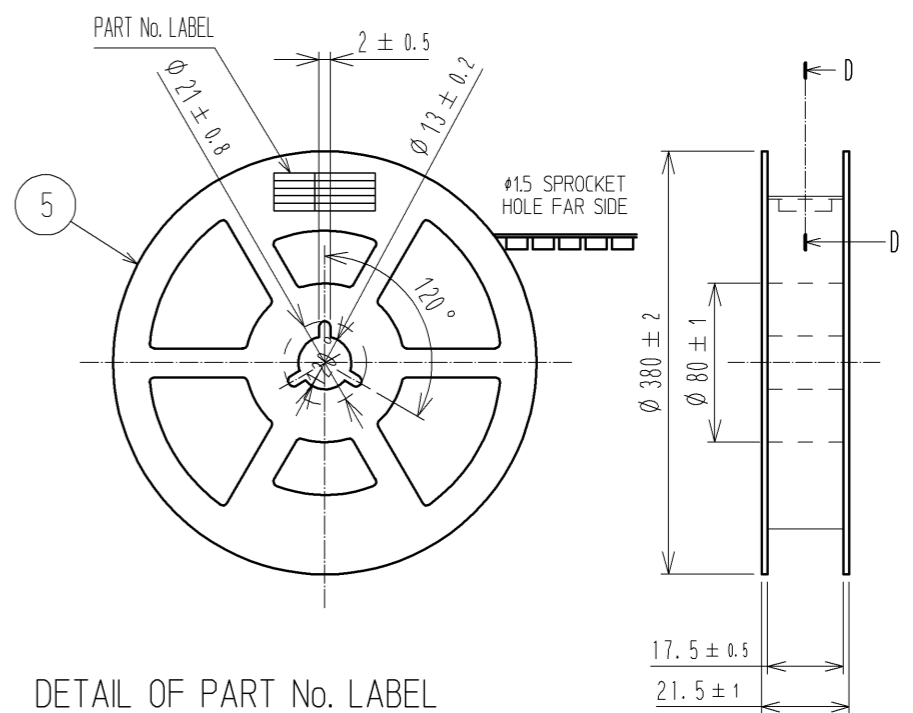
B-B (5:1)



E (10:1)



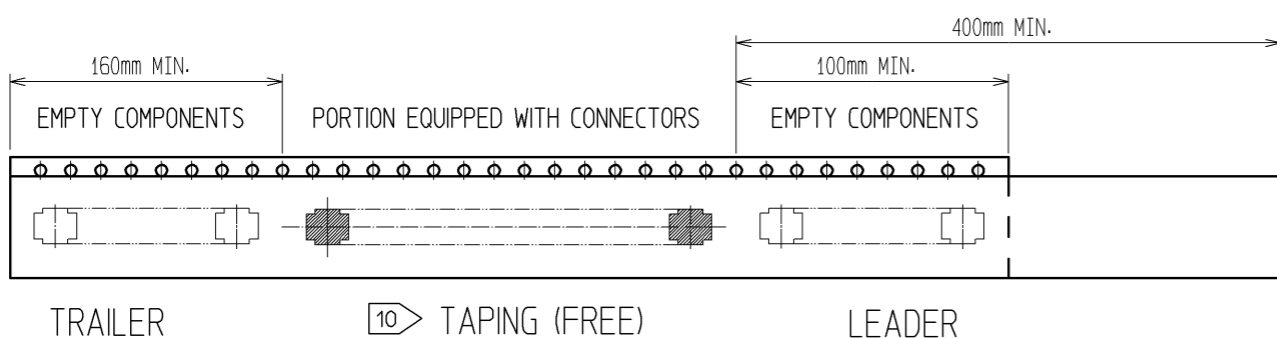
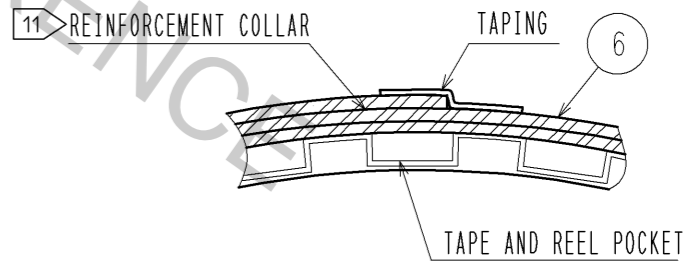
STYLE AND DIMENTION OF REEL (FREE)



DETAIL OF PART No. LABEL

SUPPLIER	
QUANTITY	
PART No.	
CODE No.	
DATE OF MANUFACTURED	
製造年月日	** ** *
製品コード	CL0684-8226-0-55
製品名	BM14JB-20DS-0.4V(55)
数量	500
納入者	ヒロセ電機(株)

D-D (FREE)



- 8. PER REEL 8000 CONNECTORS.
- 9. THE DIMENSIONS IN PARENTHESES ARE FOR REFERENCE.
- $\phi 10$ REFER TO JIS C 0806(PACKAGING OF COMPONENTS FOR AUTOMATIC HANDLING)
- $\phi 11$ AFTER PACKAGING, ROLL 2 METERS OF THE REINFORCEMENT COLLAR TO OUTER CIRCUMFERENCE OF TAPE AND REEL POCKET, AND TAPE DOWN AT THE END THE COLLAR.

HRS	DRAWING NO.	EDC3-331560-01
	PART NO.	BM14JB-20DS-0.4V(55)
	CODE NO.	CL684-8226-0-55
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